

# SN74LV594A-Q1 Automotive 8-Bit Parallel-Out Serial Shift Registers

## 1 Features

- AEC-Q100 qualified for automotive applications:
  - Device temperature grade 1:  $-40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$ ,  $T_A$
  - Device HBM ESD Classification Level 2
  - Device CDM ESD Classification Level C6
- Available in wettable flank QFN (WBQB) package
- 2 V to 5.5 V  $V_{CC}$  operation
- Maximum tpd of 6.5 ns at 5 V
- Typical  $V_{OLP}$  (output ground bounce)  $<0.8$  V at  $V_{CC} = 3.3$  V,  $T_A = 25^{\circ}\text{C}$
- Support mixed-mode voltage operation on all ports
- 8-bit serial-in, parallel-out shift registers with storage
- Independent direct overriding clears on shift and storage registers
- Independent clocks for shift and storage registers
- Latch-up performance exceeds 100 mA per JESD 78, Class II

## 2 Applications

- [Output expansion](#)
- [LED matrix control](#)
- [7-segment display control](#)

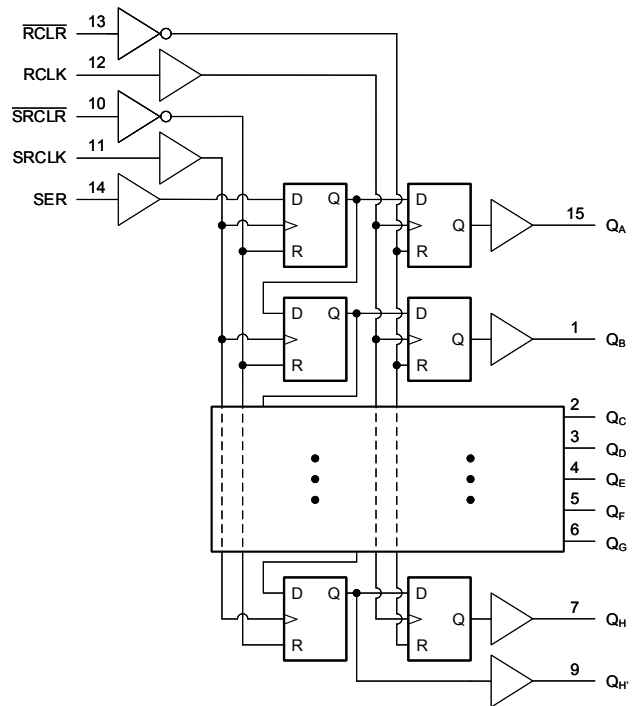
## 3 Description

The SN74LV594A-Q1 devices are 8-bit shift registers designed for 2-V to 5.5-V  $V_{CC}$  operation.

### Package Information<sup>(1)</sup>

PART NUMBER	PACKAGE	BODY SIZE (NOM)
SN74LV594A-Q1	BQB (WQFN, 16)	3.60 mm × 2.60 mm

- (1) For all available packages, see the orderable addendum at the end of the data sheet.



**Logic Diagram (Positive Logic)**



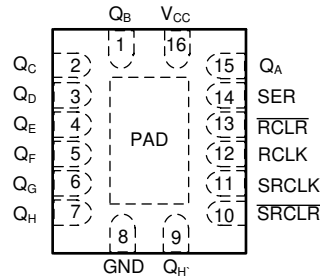
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## 4 Revision History

DATE	REVISION	NOTES
December 2022	*	Initial Release

## 5 Pin Configuration and Functions



**Figure 5-1. D, DB, or PW Package 16-Pin SOIC, SSOP, or TSSOP (Top View)**

**Table 5-1. Pin Functions**

PIN		TYPE <sup>(1)</sup>	DESCRIPTION
NAME	NO.		
Q <sub>B</sub>	1	O	Output B
Q <sub>C</sub>	2	O	Output C
Q <sub>D</sub>	3	O	Output D
Q <sub>E</sub>	4	O	Output E
Q <sub>F</sub>	5	O	Output F
Q <sub>G</sub>	6	O	Output G
Q <sub>H</sub>	7	O	Output H
GND	8	G	Ground pin
Q <sub>H</sub> '	9	O	Q <sub>H</sub> inverted
$\overline{\text{SRCLR}}$	10	I	Serial clear
SRCLK	11	I	Serial clock
RCLK	12	I	Storage clock
$\overline{\text{RCLR}}$	13	I	Storage clear
SER	14	I	Serial input
Q <sub>A</sub>	15	O	Output A
V <sub>CC</sub>	16	P	Power pin
Thermal Pad		-	Thermal Pad <sup>(1)</sup>

(1) I = Input, O = Output, I/O = Input or Output, G = Ground, P = Power

## 6 Specifications

### 6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) <sup>(1)</sup>

		MIN	MAX	UNIT	
V <sub>CC</sub>	Supply voltage	-0.5	7	V	
V <sub>I</sub>	Input voltage <sup>(2)</sup>	-0.5	7	V	
V <sub>O</sub>	Voltage range applied to any output in the high-impedance or power-off state <sup>(2)</sup>	-0.5	7	V	
V <sub>O</sub>	Output voltage <sup>(2) (3)</sup>	-0.5	V <sub>CC</sub> + 0.5	V	
I <sub>IK</sub>	Input clamp current	V <sub>I</sub> < 0	-20	mA	
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0	-50	mA	
I <sub>O</sub>	Continuous output current	V <sub>O</sub> = 0 to V <sub>CC</sub>	-25	25	mA
T <sub>stg</sub>	Storage temperature	-65	150	°C	

- (1) Operation outside the *Absolute Maximum Ratings* may cause permanent device damage. *Absolute Maximum Ratings* do not imply functional operation of the device at these or any other conditions beyond those listed under *Recommended Operating Conditions*. If used outside the Recommended Operating Conditions but within the *Absolute Maximum Ratings*, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The value is limited to 5.5 V maximum.

### 6.2 ESD Ratings

		VALUE	UNIT
V <sub>(ESD)</sub>	Electrostatic discharge	Human body model (HBM), per AEC Q100-002 HBM ESD Classification Level 2 <sup>(1)</sup>	±2000
		Charged device model (CDM), per AEC Q100-011 CDM ESD Classification Level C6	±1000

- (1) AEC Q100-002 indicate that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

### 6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage	2	5.5	V
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 2 V	1.5	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	V <sub>CC</sub> × 0.7	
		V <sub>CC</sub> = 3 V to 3.6 V	V <sub>CC</sub> × 0.7	
		V <sub>CC</sub> = 4.5 V to 5.5 V	V <sub>CC</sub> × 0.7	
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 2 V	0.5	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	V <sub>CC</sub> × 0.3	
		V <sub>CC</sub> = 3 V to 3.6 V	V <sub>CC</sub> × 0.3	
		V <sub>CC</sub> = 4.5 V to 5.5 V	V <sub>CC</sub> × 0.3	
V <sub>I</sub>	Input voltage	0	5.5	V
V <sub>O</sub>	Output voltage	0	V <sub>CC</sub>	V
I <sub>OH</sub>	High-level input current	V <sub>CC</sub> = 2 V	-50	μA
		V <sub>CC</sub> = 2.3 V to 2.7 V	-2	
		V <sub>CC</sub> = 3 V to 3.6 V	6	
		V <sub>CC</sub> = 4.5 V to 5.5 V	-12	
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 2 V	50	μA
		V <sub>CC</sub> = 2.3 V to 2.7 V	2	
		V <sub>CC</sub> = 3 V to 3.6 V	6	
		V <sub>CC</sub> = 4.5 V to 5.5 V	12	
Δt/Δv	Input transition rise or fall rate	V <sub>CC</sub> = 2.3 V to 2.7 V	200	ns/V
		V <sub>CC</sub> = 3 V to 3.6 V	100	
		V <sub>CC</sub> = 4.5 V to 5.5 V	20	
T <sub>A</sub>	Operating free-air temperature	-40	125	°C

(1) All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report *Implications of Slow or Floating CMOS Inputs*, [SCBA004](#).

### 6.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		SN74LV594A-Q1	UNIT
		BQB (WQFN)	
		16 PINS	
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	86.0	°C/W
R <sub>θJC(top)</sub>	Junction-to-case (top) thermal resistance	82.6	
R <sub>θJB</sub>	Junction-to-board thermal resistance	54.9	
ψ <sub>JT</sub>	Junction-to-top characterization parameter	9.5	
ψ <sub>JB</sub>	Junction-to-board characterization parameter	54.9	
ψ <sub>JC</sub>	Junction-to-bottom characterization parameter	32.5	

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](#).

## 6.5 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	UNIT
V <sub>OH</sub>	I <sub>OH</sub> = -50 μA	2 V to 5.5 V	V <sub>CC</sub> - 0.1			V
	I <sub>OH</sub> = -2 μA	2.3 V	2			
	I <sub>OH</sub> = -6 μA	3 V	2.48			
	I <sub>OH</sub> = -12 μA	4.5 V	3.8			
V <sub>OL</sub>	I <sub>OH</sub> = -50 μA	2 V to 5.5 V	0.1			V
	I <sub>OH</sub> = -2 μA	2.3 V	0.4			
	I <sub>OH</sub> = -6 μA	3 V	0.44			
	I <sub>OH</sub> = -12 μA	4.5 V	0.55			
I <sub>I</sub>	V <sub>I</sub> = 5.5 V or GND	0 to 5.5 V	±1			μA
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	5.5 V	20			μA
I <sub>off</sub>	V <sub>I</sub> or V <sub>O</sub> = 0 to 5.5 V	0	5			μA
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	3.3 V	3.5			pF

## 6.6 Switching Characteristics: V<sub>CC</sub> = 2.5 V ± 0.2 V

over recommended operating free-air temperature range (unless otherwise noted). See [Figure 6-1](#).

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T <sub>A</sub> = 25°C			-40°C TO 125°C		UNIT	
				MIN	TYP	MAX	MIN	MAX		
f <sub>max</sub>			C <sub>L</sub> = 15 pF	65	80		35		MHz	
			C <sub>L</sub> = 50 pF	60	70		30			
t <sub>PLH</sub>	SRCLK	Q <sub>A</sub> - Q <sub>H</sub>	C <sub>L</sub> = 15 pF		6.4	10.6	1	12.5	ns	
t <sub>PHL</sub>					6.3	10.4	1	12.5		
t <sub>PLH</sub>	RCLK	Q <sub>H'</sub>			7.4	12.1	1	15		
t <sub>PHL</sub>					7.2	11.6	1	15		
t <sub>PHL</sub>	RCLK	Q <sub>A</sub> - Q <sub>H</sub>			7.9	12.7	1	15.5		
t <sub>PHL</sub>					7.4	11.9	1	15.5		
t <sub>PLH</sub>	SRCLR	Q <sub>A</sub> - Q <sub>H</sub>			9.5	14.1	1	17		ns
t <sub>PHL</sub>					10.8	15.5	1	19.5		
t <sub>PLH</sub>	RCLR	Q <sub>H'</sub>		10.6	15.7	1	18.5			
t <sub>PHL</sub>				11.3	16.1	1	20.5			
t <sub>PHL</sub>	RCLR	Q <sub>A</sub> - Q <sub>H</sub>		12.1	17.4	1	21			
t <sub>PHL</sub>				11.6	16.5	1	20.6			

### 6.7 Switching Characteristics: $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$

over recommended operating free-air temperature range (unless otherwise noted). See [Figure 6-1](#).

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			$-40^\circ\text{C TO } 125^\circ\text{C}$		UNIT
				MIN	TYP	MAX	MIN	MAX	
$f_{\max}$			$C_L = 15\text{ pF}$	80	120		60		MHz
			$C_L = 50\text{ pF}$	55	105		40		
$t_{PLH}$	SRCLK	$Q_A - Q_H$	$C_L = 15\text{ pF}$		4.6	8	1	10.5	ns
$t_{PHL}$					4.9	8.2	1	10.5	
$t_{PLH}$	$Q_H$			5.4	9.1	1	11.5		
$t_{PHL}$				5.5	9.2	1	11.6		
$t_{PHL}$	RCLK	$Q_A - Q_H$			6	9.8	1	12.1	
				$Q_H$		5.6	9.2	1	
$t_{PLH}$	$\overline{\text{SRCLR}}$	$Q_A - Q_H$	$C_L = 50\text{ pF}$				1	12.5	ns
$t_{PHL}$							1	15	
$t_{PLH}$	$Q_H$					1	14		
$t_{PHL}$						1	15.5		
$t_{PHL}$	RCLR	$Q_A - Q_H$					1	16.1	
				$Q_H$				1	

### 6.8 Switching Characteristics: $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$

over recommended operating free-air temperature range (unless otherwise noted). See [Figure 6-1](#).

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			$-40^\circ\text{C TO } 125^\circ\text{C}$		UNIT
				MIN	TYP	MAX	MIN	MAX	
$f_{\max}$			$C_L = 15\text{ pF}$	135	170		105		MHz
			$C_L = 50\text{ pF}$	120	140		85		
$t_{PLH}$	SRCLK	$Q_A - Q_H$	$C_L = 15\text{ pF}$		3.3	6.2	1	8	ns
$t_{PHL}$					3.7	6.5	1	8.5	
$t_{PLH}$	$Q_H$			3.7	6.8	1	8.5		
$t_{PHL}$				4.1	7.2	1	9		
$t_{PHL}$	RCLK	$Q_A - Q_H$			4.5	7.6	1	9.5	
				$Q_H$		4.1	7.1	1	
$t_{PLH}$	$\overline{\text{SRCLR}}$	$Q_A - Q_H$	$C_L = 50\text{ pF}$		4.9	7.8	1	9.6	ns
$t_{PHL}$					5.8	8.9	1	11	
$t_{PLH}$	$Q_H$			5.5	8.6	1	10.5		
$t_{PHL}$				6	9.2	1	11.5		
$t_{PHL}$	RCLR	$Q_A - Q_H$			6.6	10	1	12	
				$Q_H$		6	9.2	1	

## 6.9 Timing Requirements: $V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$

over recommended operating free-air temperature range. See [Figure 6-1](#).

		$T_A = 25^\circ\text{C}$		$-40^\circ\text{C TO } 125^\circ\text{C}$		UNIT
		MIN	MAX	MIN	MAX	
$t_w$	Pulse duration	RCLK or SRCLK high or low		8.5		ns
		RCKR or SCRCLR low		7.5		
$t_{su}$	Setup time	SER before SRCLK $\uparrow$		6		ns
		SRCLK $\uparrow$ before RCLK $\uparrow$		10		
		SCRCLR low before RCLK $\uparrow$ <sup>(1)</sup>		10.5		
		SRCLR high (inactive) before SRCLK $\uparrow$		7.5		
		RCLK high (inactive) before RCLK $\uparrow$		8.5		
$t_h$	Hold time	SER after SRCLK $\uparrow$		2		ns

- (1) This setup time allows the storage register to receive stable data from the shift register. The clocks can be tied together, in which case the shift register is one clock pulse ahead of the storage register.

## 6.10 Timing Requirements: $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$

over recommended operating free-air temperature range. See [Figure 6-1](#).

		$T_A = 25^\circ\text{C}$		$-40^\circ\text{C TO } 125^\circ\text{C}$		UNIT
		MIN	MAX	MIN	MAX	
$t_w$	Pulse duration	RCLK or SRCLK high or low		6.5		ns
		RCKR or SCRCLR low		6		
$t_{su}$	Setup time	SER before SRCLK $\uparrow$		4		ns
		SRCLK $\uparrow$ before RCLK $\uparrow$		9.5		
		SCRCLR low before RCLK $\uparrow$ <sup>(1)</sup>		10		
		SRCLR high (inactive) before SRCLK $\uparrow$		5.5		
		RCLK high (inactive) before RCLK $\uparrow$		6		
$t_h$	Hold time	SER after SRCLK $\uparrow$		2		ns

- (1) This setup time allows the storage register to receive stable data from the shift register. The clocks can be tied together, in which case the shift register is one clock pulse ahead of the storage register.

## 6.11 Timing Requirements: $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$

over recommended operating free-air temperature range. See [Figure 6-1](#).

		$T_A = 25^\circ\text{C}$		$-40^\circ\text{C TO } 125^\circ\text{C}$		UNIT
		MIN	MAX	MIN	MAX	
$t_w$	Pulse duration	RCLK or SRCLK high or low		6		ns
		RCKR or SCRCLR low		6.2		
$t_{su}$	Setup time	SER before SRCLK $\uparrow$		3.5		ns
		SRCLK $\uparrow$ before RCLK $\uparrow$		6		
		SCRCLR low before RCLK $\uparrow$ <sup>(1)</sup>		5.5		
		SRCLR high (inactive) before SRCLK $\uparrow$		4		
		RCLK high (inactive) before RCLK $\uparrow$		4.5		
$t_h$	Hold time	SER after SRCLK $\uparrow$		2.5		ns

- (1) This setup time allows the storage register to receive stable data from the shift register. The clocks can be tied together, in which case the shift register is one clock pulse ahead of the storage register.



### 6.12 Noise Characteristics

over operating free-air temperature range (unless otherwise noted),  $V_{CC} = 3.3\text{ V}$ ,  $C_L = 50\text{ pF}$ ,  $T_A = 25^\circ\text{C}^{(1)}$

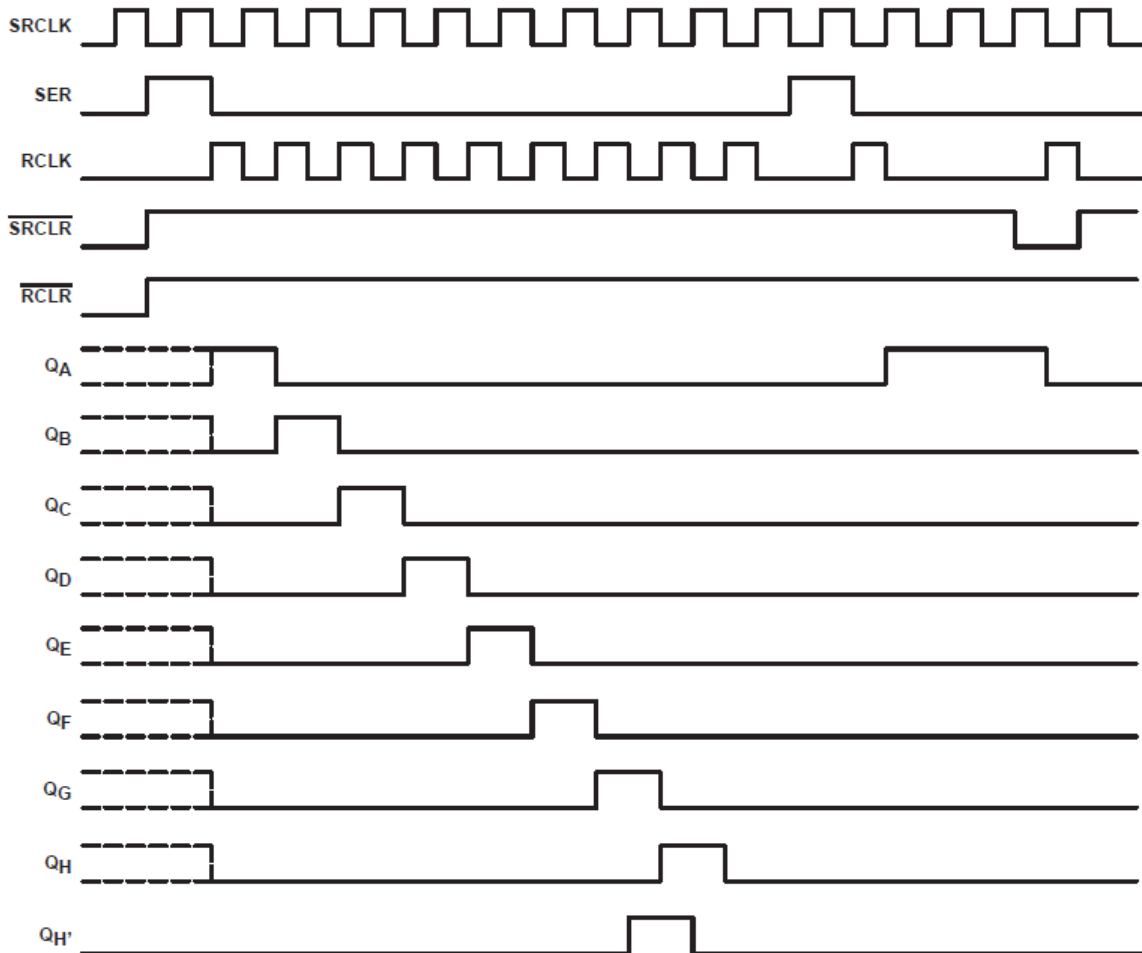
PARAMETER		MIN	TYP	MAX	UNIT
$V_{OL(P)}$	Quiet output, maximum dynamic $V_{OL}$		0.5	0.8	V
$V_{OL(V)}$	Quiet output, minimum dynamic $V_{OL}$		-0.1	-0.8	V
$V_{OH(V)}$	Quiet output, minimum dynamic $V_{OH}$		2.8		V
$V_{IH(V)}$	High-level dynamic input voltage	2.31			V
$V_{IL(V)}$	Low-level dynamic input voltage			0.99	V

(1) Characteristics are for surface-mount packages only.

### 6.13 Operating Characteristics

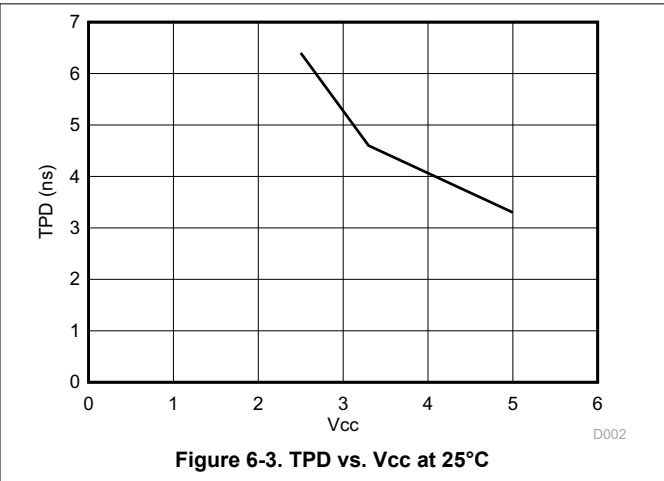
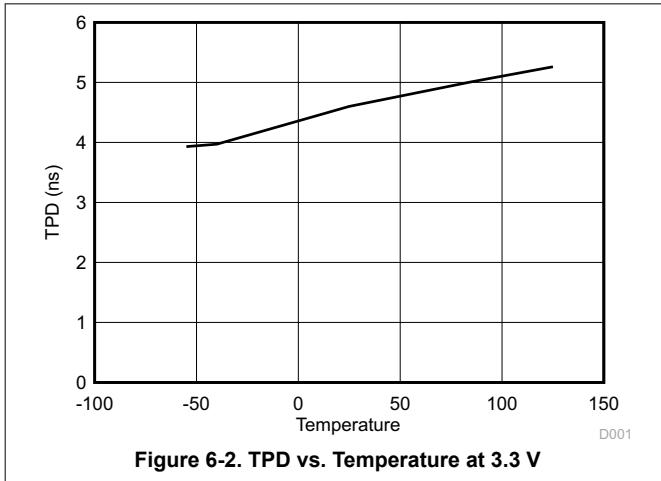
$T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	$V_{CC}$	TYP	UNIT
$C_{pd}$	Power dissipation capacitance	f = 10 MHz	3.3 V	93	pF
			5 V	112	

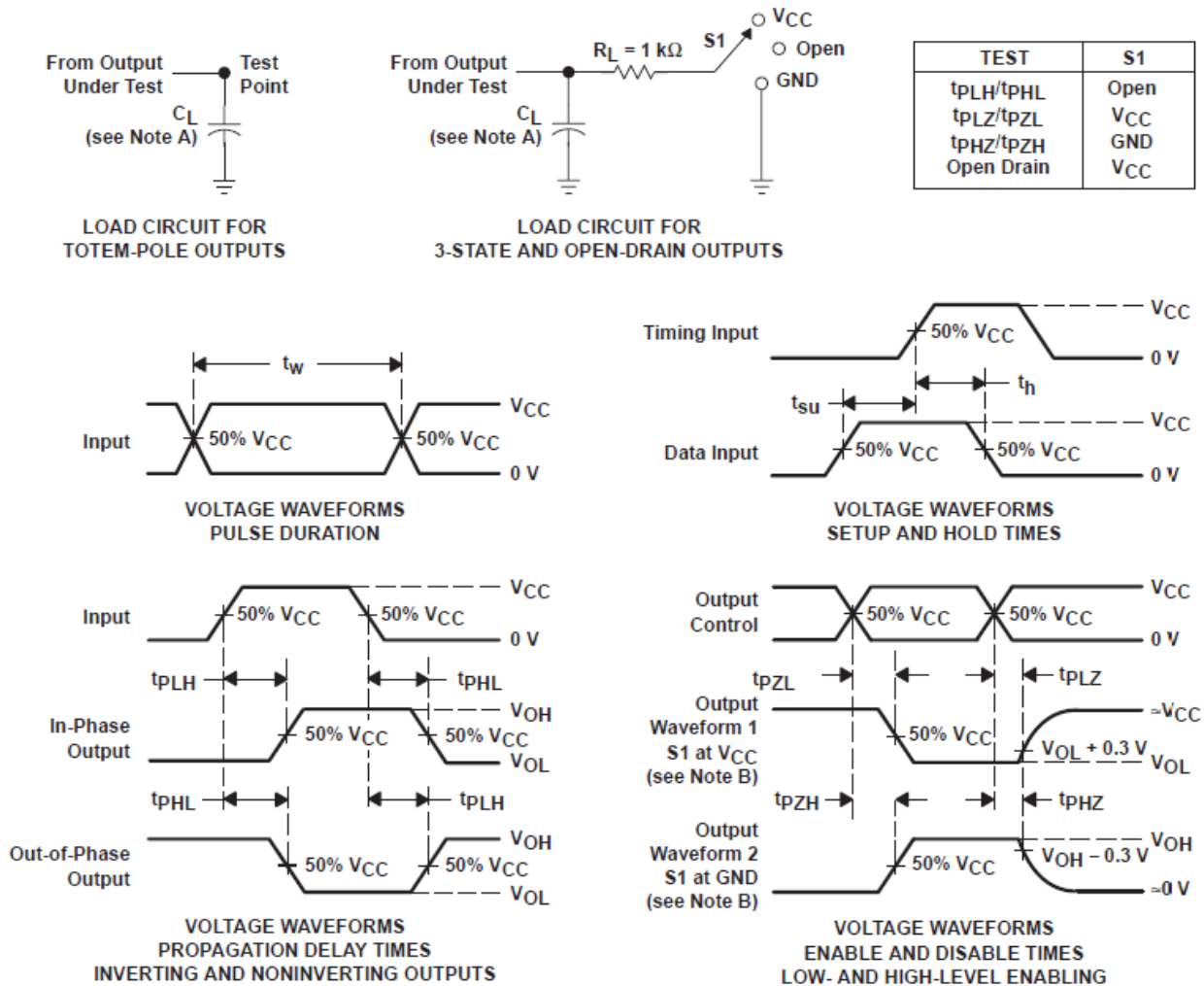


**Figure 6-1. Timing Diagram**

## 6.14 Typical Characteristics



## 7 Parameter Measurement Information



- NOTES:
- A.  $C_L$  includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1\text{ MHz}$ ,  $Z_O = 50\ \Omega$ ,  $t_r \leq 3\text{ ns}$ ,  $t_f \leq 3\text{ ns}$ .
  - D. The outputs are measured one at a time, with one input transition per measurement.
  - E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - G.  $t_{PHL}$  and  $t_{PLH}$  are the same as  $t_{pd}$ .
  - H. All parameters and waveforms are not applicable to all devices.

Figure 7-1. Load Circuit and Voltage Waveforms



### 8.3 Feature Description

The device's wide operating range allows it to be used in a variety of systems that use different logic levels. The low propagation delay allows fast switching and higher speeds of operation. In addition, the low ground bounce stabilizes the performance of non-switching outputs while another output is switching.

### 8.4 Device Functional Modes

**Table 8-1. Function Table**

INPUTS					FUNCTION
SER	SRCLK	$\overline{\text{SRCLR}}$	RCLK	$\overline{\text{RCLR}}$	
X	X	L	X	X	Shift register is cleared.
L	↑	H	X	X	First stage of shift register goes low. Other stages store the data of previous stage, respectively.
H	↑	H	X	X	First stage of shift register goes high. Other stages store the data of previous stage, respectively.
L	↓	H	X	X	Shift register state is not changed.
X	X	X	X	L	Storage register is cleared.
X	X	X	↑	H	Shift register data is stored in the storage register.
X	X	X	↓	H	Storage register state is not changed.

## 9 Application and Implementation

### Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

### 9.1 Application Information

The SN74LV594A-Q1 is a low drive CMOS device that can be used for a multitude of bus interface type applications where output ringing is a concern. The low drive and slow edge rates will minimize overshoot and undershoot on the outputs.

### 9.2 Typical Application

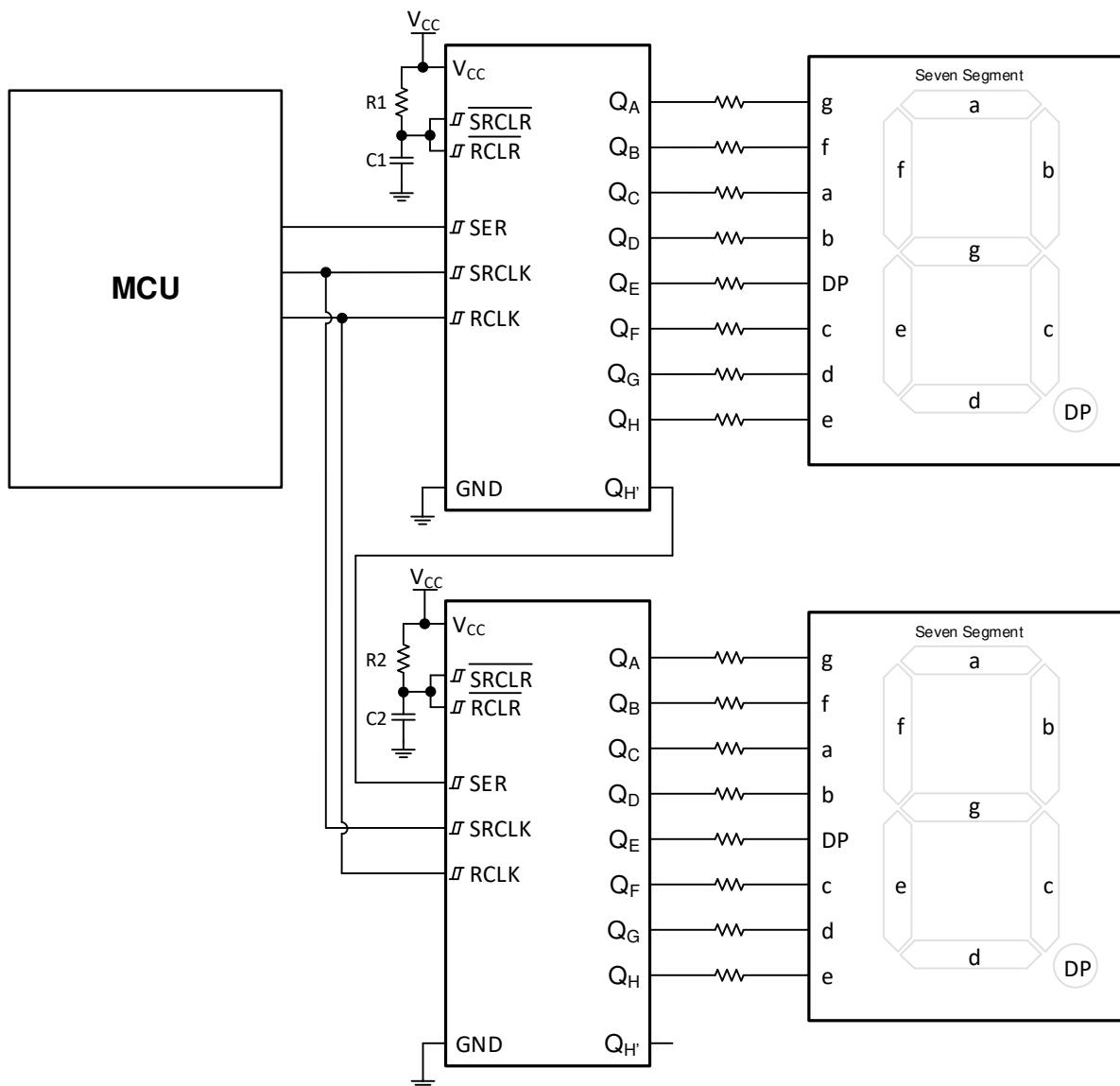


Figure 9-1. Typical Application Schematic

### 9.2.1 Design Requirements

This device uses CMOS technology and has balanced output drive. Take care to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive will also create fast edges into light loads, so consider routing and load conditions to prevent ringing.

### 9.2.2 Detailed Design Procedure

- Recommended input conditions:
  - Rise time and fall time specs. See  $(\Delta t/\Delta V)$  in [Section 6.3](#).
  - Specified high and low levels. See  $(V_{IH}$  and  $V_{IL})$  in [Section 6.3](#).
  - Inputs are overvoltage tolerant allowing them to go as high as 5.5 V at any valid  $V_{CC}$ .
- Recommended output conditions:
  - Load currents should not exceed 25 mA per output and 50 mA total for the part.
  - Outputs should not be pulled above  $V_{CC}$ .

### 9.2.3 Application Curves

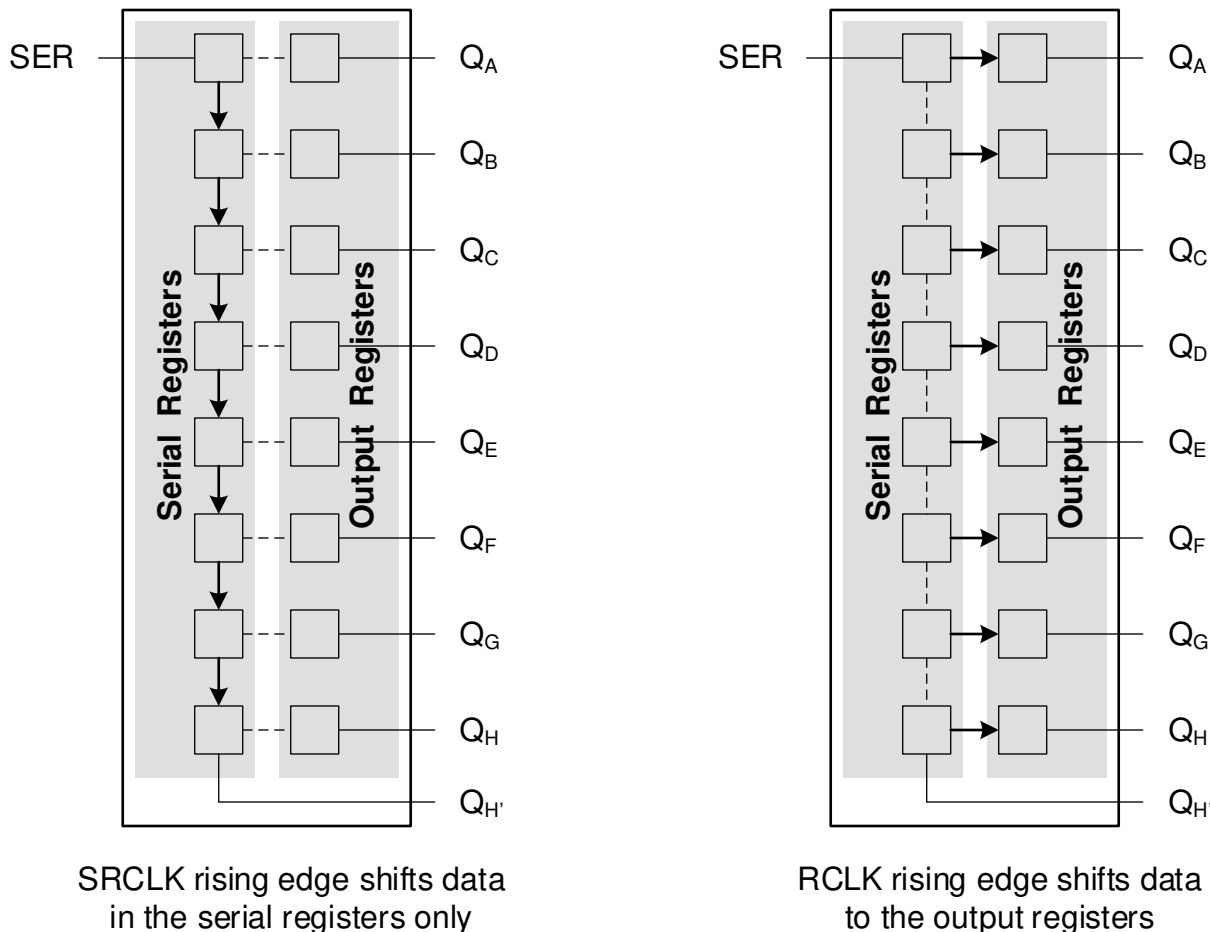


Figure 9-2. Simplified functional diagram showing clock operation

## 10 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the [Recommended Operating Conditions](#). Each  $V_{CC}$  terminal should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, TI recommends a 0.1- $\mu\text{F}$  capacitor and if there are multiple  $V_{CC}$  terminals then TI recommends a 0.01- $\mu\text{F}$  or 0.022- $\mu\text{F}$  capacitor for each power terminal. Multiple bypass capacitors can be paralleled to reject different frequencies of noise. Frequencies of 0.1  $\mu\text{F}$  and 1  $\mu\text{F}$  are commonly used in parallel. The bypass capacitor should be installed as close as possible to the power terminal for best results.



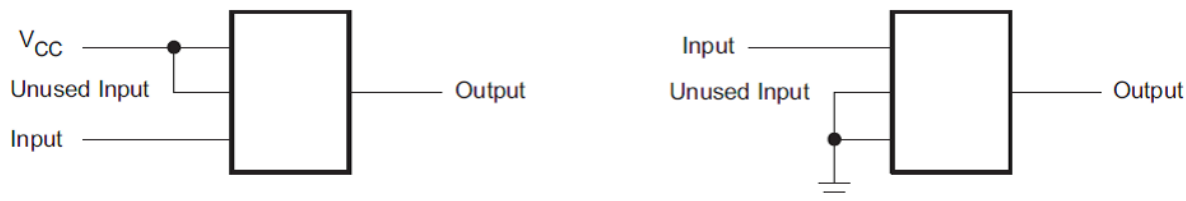
## 11 Layout

### 11.1 Layout Guidelines

When using multiple bit logic devices inputs should not ever float.

In many cases, functions or parts of functions of digital logic devices are unused, for example, when only two inputs of a triple-input AND gate are used or only three of the four buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. Specified below are the rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or  $V_{CC}$  whichever make more sense or is more convenient. Floating outputs is generally acceptable, unless the part is a transceiver. If the transceiver has an output enable pin, then it will disable the outputs section of the part when asserted. This will not disable the input section of the I.O's so they also cannot float when disabled.

### 11.2 Layout Example



**Figure 11-1. Layout Example**

## 12 Device and Documentation Support

### 12.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](http://ti.com). Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 12.2 Support Resources

TI E2E™ [support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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### 12.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.  
All trademarks are the property of their respective owners.

### 12.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 12.5 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

## 13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LV594AQWBQBRQ1	ACTIVE	WQFN	BQB	16	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV594Q	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF SN74LV594A-Q1 :**

- Catalog : [SN74LV594A](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

## GENERIC PACKAGE VIEW

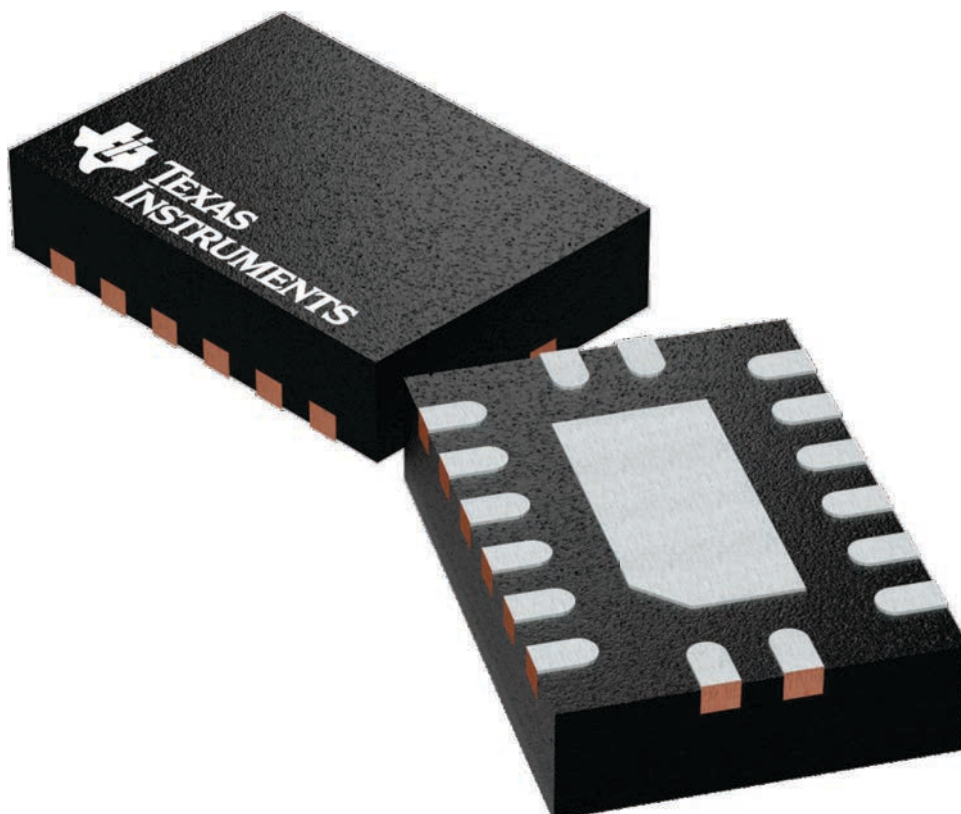
**BQB 16**

**WQFN - 0.8 mm max height**

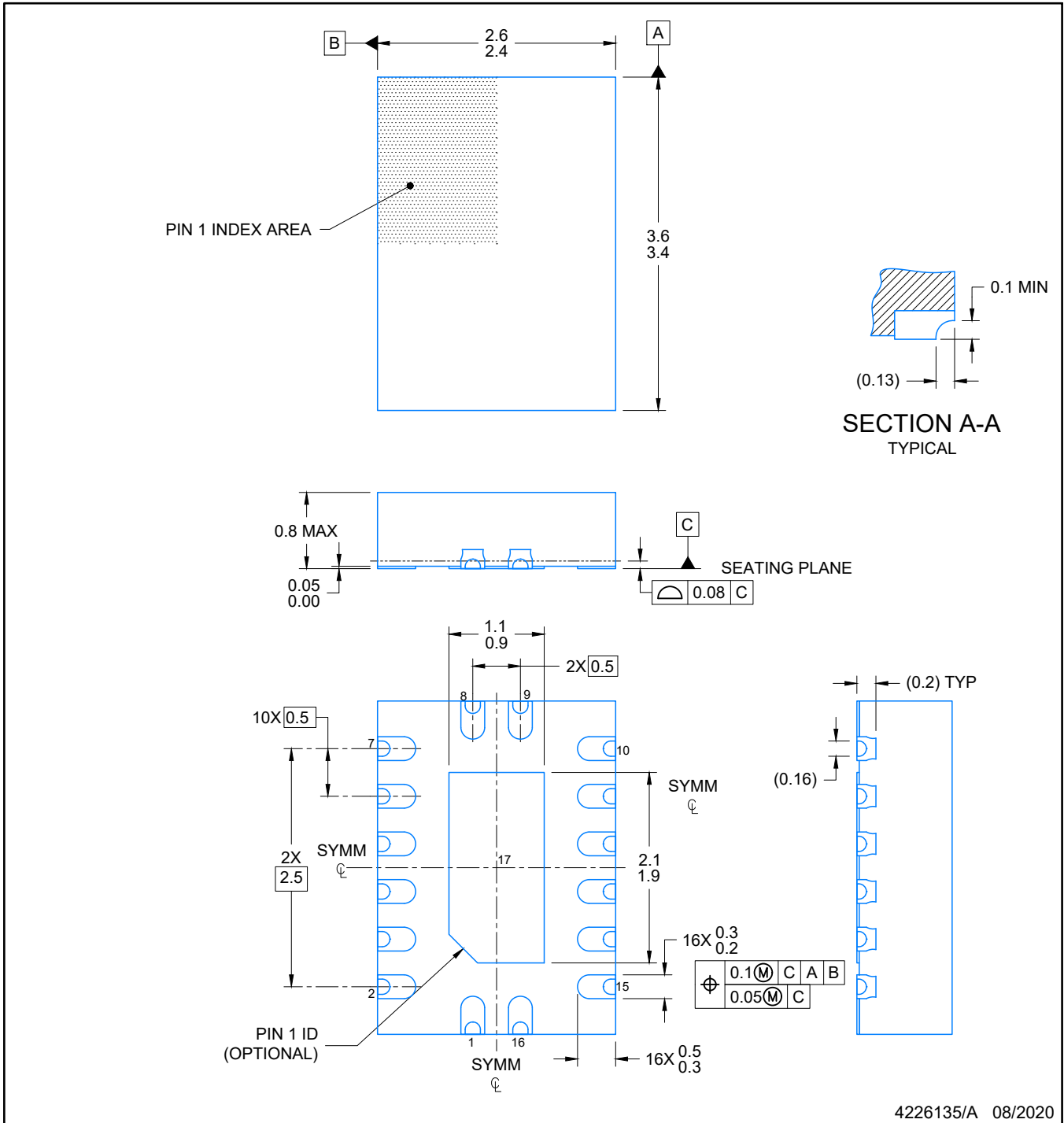
2.5 x 3.5, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

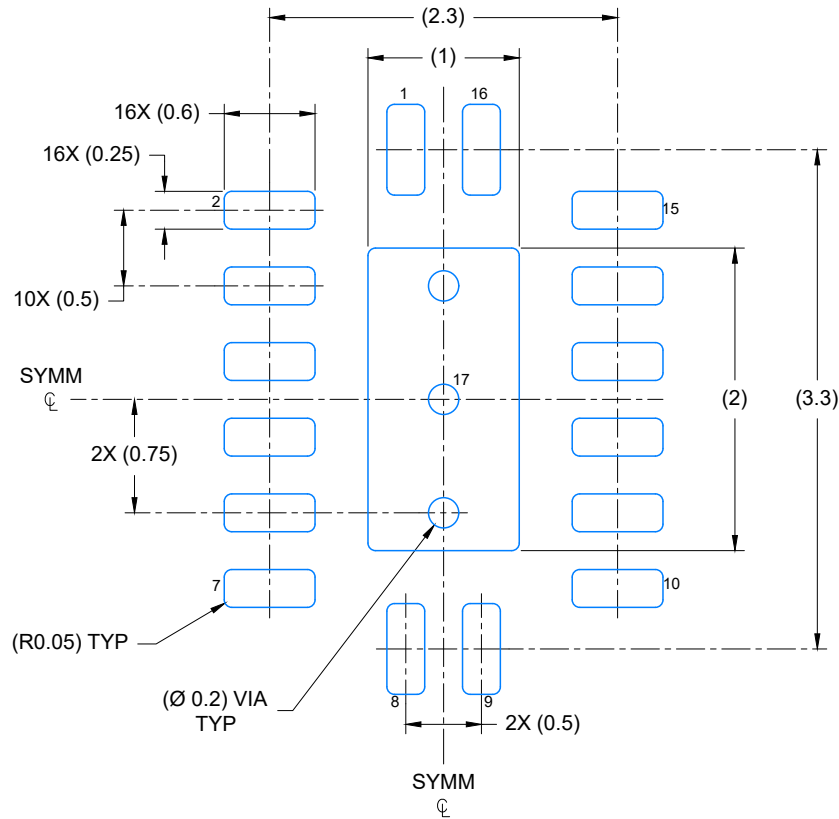


4226161/A



**NOTES:**

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for optimal thermal and mechanical performance.

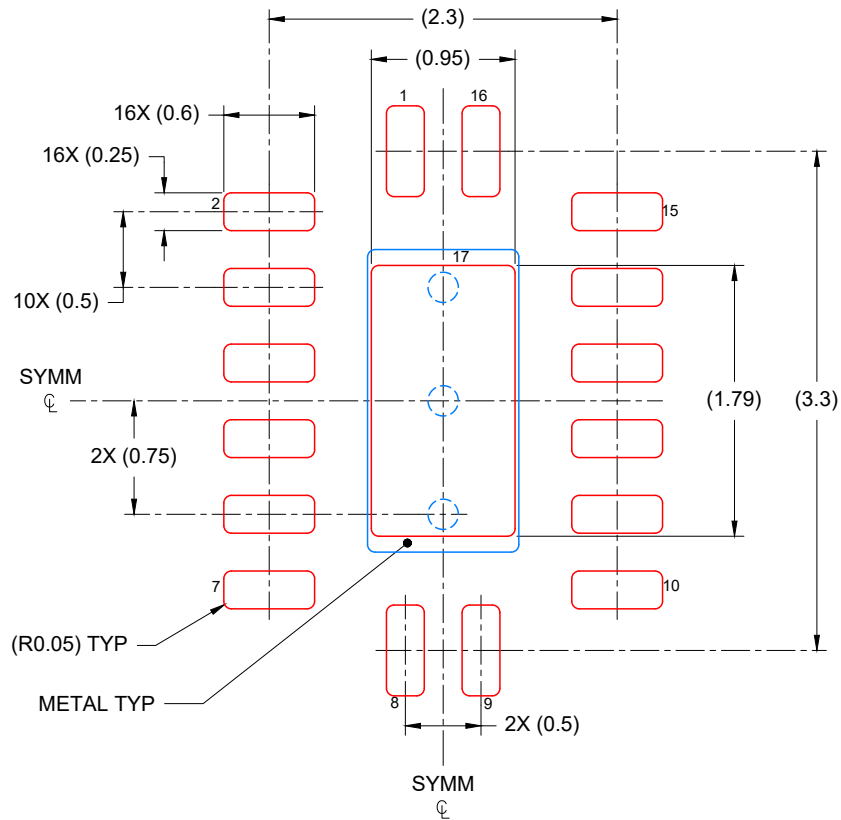


LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 20X

4226135/A 08/2020

NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/sluea271](http://www.ti.com/lit/sluea271)).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.



SOLDER PASTE EXAMPLE  
 BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD  
 85% PRINTED COVERAGE BY AREA  
 SCALE: 20X

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NOTES: (continued)

- 6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.



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